

What is claimed is:

- 1 1. An apparatus comprising:
2 a first signal path connected to a first plane via a plated hole;
3 a first metal flood connected to the plated hole to form a first plate;
4 a second signal path on a second plane; and
5 a second metal flood connected to the second signal path to form a
6 second plate above the first plate.
- 1 2. The apparatus of claim 1 wherein the first and second plates form a
2 capacitance.
- 1 3. The apparatus of claim 1 wherein the first plate is connected at one of a
2 first receiver end and a first driver end of the first signal path.
- 1 4. The apparatus of claim 1 wherein the second plate is connected at one of
2 a second receiver end and a second driver end of the second signal path.
- 1 5. The apparatus of claim 4 wherein the first and second signal paths are
2 adjacent to each other.
- 1 6. The apparatus of claim 1 wherein the first plane is one of a ground plane
2 and a power plane.
- 1 7. The apparatus of claim 6 wherein the first metal flood is an isolated area
2 in the first plane.
- 1 8. A method comprising:

2 connecting a first signal path to a first plane via a plated hole;
3 forming a first plate by connecting a first metal flood to the plated hole;
4 and
5 connecting a second metal flood to a second signal path on a second
6 plane to form a second plate above the first plate.

1 9. The method of claim 8 wherein the first and second plates form a
2 capacitance.

1 10. The method of claim 8 wherein the first plate is connected at one of a
2 first receiver end and a first driver end of the first signal path.

1 11. The method of claim 8 wherein the second plate is connected at one of a
2 second receiver end and a second driver end of the second signal path.

1 12. The method of claim 11 wherein the first and second signal paths are
2 adjacent to each other.

1 13. The method of claim 8 wherein the first plane is one of a ground plane
2 and a power plane.

1 14. The method of claim 13 wherein the first metal flood is an isolated area in
2 the first plane.

1 15. A system comprising:
2 a through hole component to hold a component that is mounted on a
3 board, the through hole component having one of a first receiver end and a first driver
4 end; a signal carrying module coupled to the through hole component to carry signal,
5 the signal carrying module comprising:

6 a first signal path connected to a first plane via a plated hole;
7 a first metal flood connected to the plated hole to form a first plate;
8 a second signal path on a second plane; and
9 a second metal flood connected to the second signal path to form a
10 second plate above the first plate.

1 16. The system of claim 15 wherein the first and second plates form a
2 capacitance.

1 17. The system of claim 15 wherein the first plate is connected at one of the
2 first receiver end and the first driver end of the first signal path.

1 18. The system of claim 15 wherein the second plate is connected at one of a
2 second receiver end and a second driver end of the second signal path.

1 19. The system of claim 18 wherein the first and second signal paths are
2 adjacent to each other.

1 20. The system of claim 15 wherein the first plane is one of a ground plane
2 and a power plane.

1 21. The system of claim 20 wherein the first metal flood is an isolated area in
2 the first plane.

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